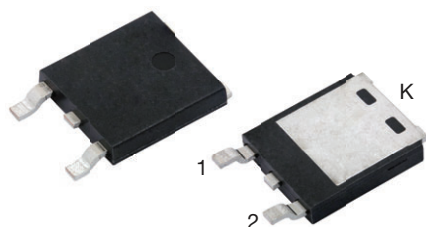


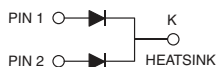
# High Current Density Surface Mount Trench MOS Barrier Schottky Rectifier

Ultra Low  $V_F = 0.60\text{ V}$  at  $I_F = 5\text{ A}$

TMBS® eSMP® Series



SlimDPAK



## FEATURES

- Very low profile - typical height of 1.3 mm
- Trench MOS Schottky technology
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

## MECHANICAL DATA

**Case:** SlimDPAK

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	40 A
$V_{RRM}$	150 V
$I_{FSM}$	240 A
$V_F$ at $I_F = 20\text{ A}$ ( $T_A = 125\text{ °C}$ )	0.76 V
$T_J$ max.	150 °C
Package	SlimDPAK
Diode variation	Dual common cathode

## MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V40PW15C	UNIT
Device marking code		V40PW15C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig. 1)	per device $I_{F(AV)}^{(1)}$	40	A
	per diode $I_{F(AV)}^{(1)}$	20	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	$I_{FSM}$	240	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +150	°C

### Note

(1) With infinite heat sink

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Maximum instantaneous forward voltage	I <sub>F</sub> = 5.0 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.77	-	V
	I <sub>F</sub> = 10 A			0.97	-	
	I <sub>F</sub> = 20 A			1.36	1.45	
	I <sub>F</sub> = 5.0 A	T <sub>A</sub> = 125 °C		0.6	-	
	I <sub>F</sub> = 10 A			0.69	-	
	I <sub>F</sub> = 20 A			0.76	0.84	
Reverse current	V <sub>R</sub> = 100 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.01	-	mA
		T <sub>A</sub> = 125 °C		3	-	
	V <sub>R</sub> = 150 V	T <sub>A</sub> = 25 °C		-	0.5	
		T <sub>A</sub> = 125 °C		6	20	
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	870	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: pulse width  $\leq 5\text{ ms}$

**THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V40PW15C	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	55	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(3)}$	1.5	

**Notes**

- (1) The heat generated must be less than thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (2) Free air, mounted on recommended copper pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient  
 (3) Mounted on infinite heat sink; thermal resistance  $R_{\theta JM}$  - junction-to-mount

**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V40PW15C-M3/I	0.20	I	4500	13" diameter plastic tape and reel
V40PW15CHM3/I <sup>(1)</sup>	0.20	I	4500	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

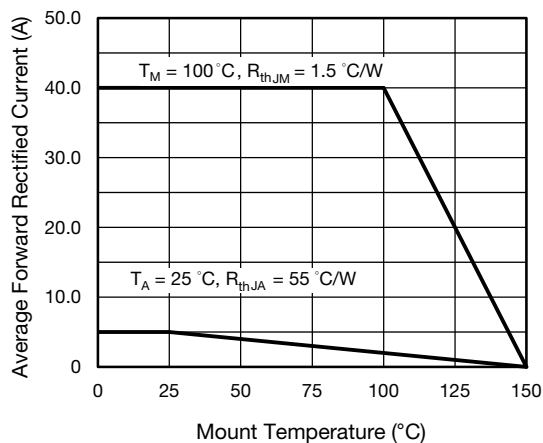
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

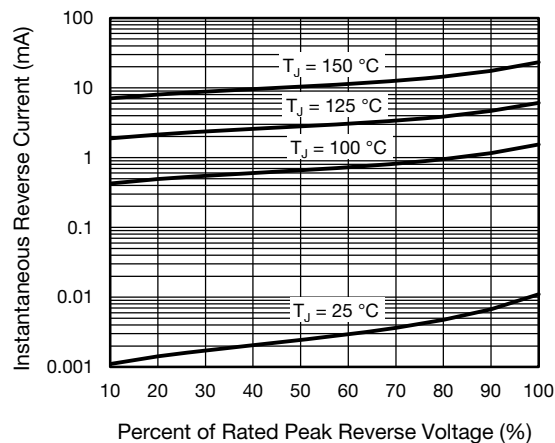


Fig. 4 - Typical Reverse Leakage Characteristics

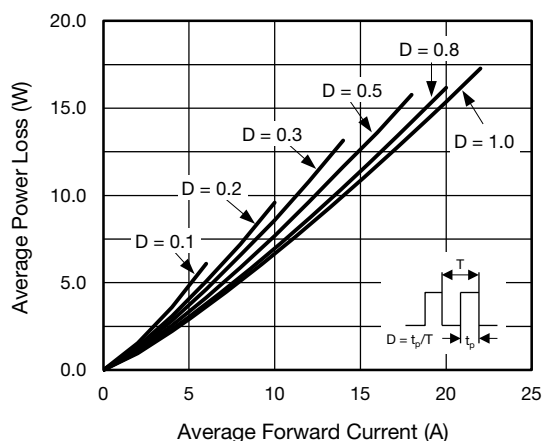


Fig. 2 - Forward Power Loss Characteristics

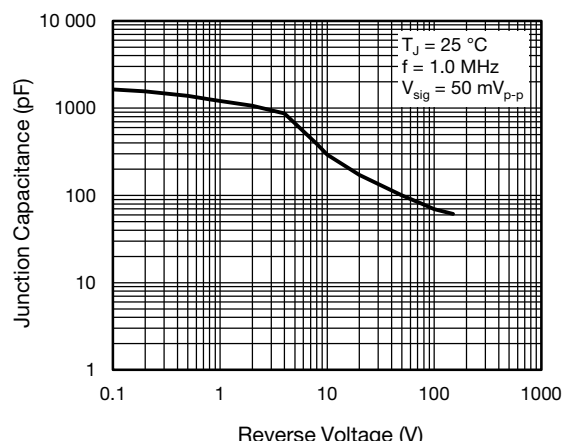


Fig. 5 - Typical Junction Capacitance

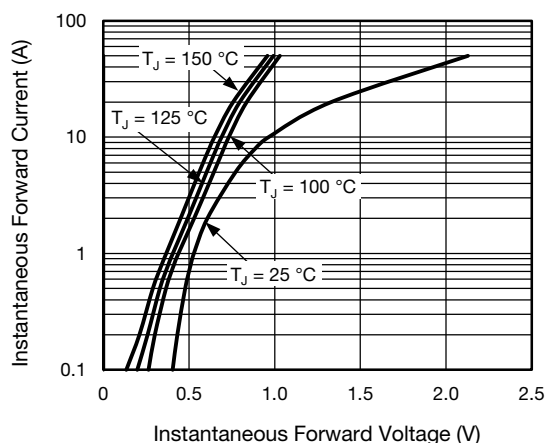


Fig. 3 - Typical Instantaneous Forward Characteristics

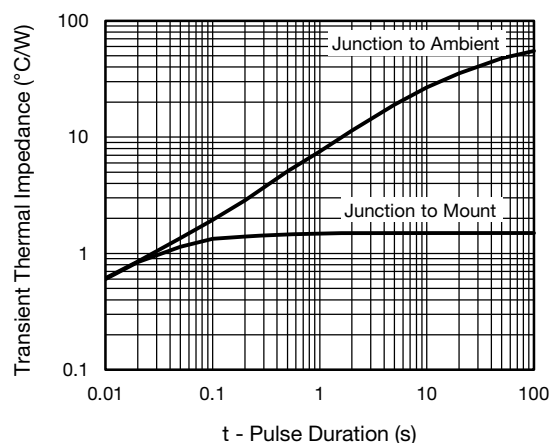


Fig. 6 - Typical Transient Thermal Impedance

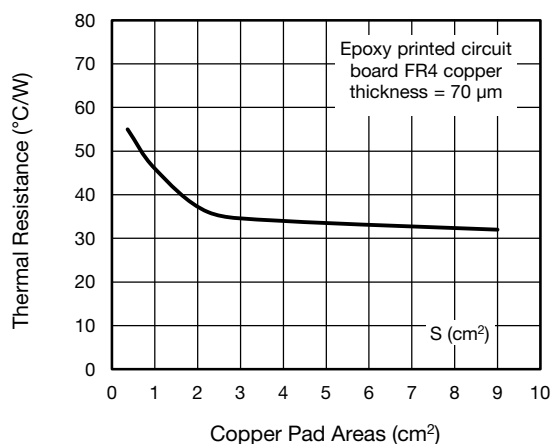
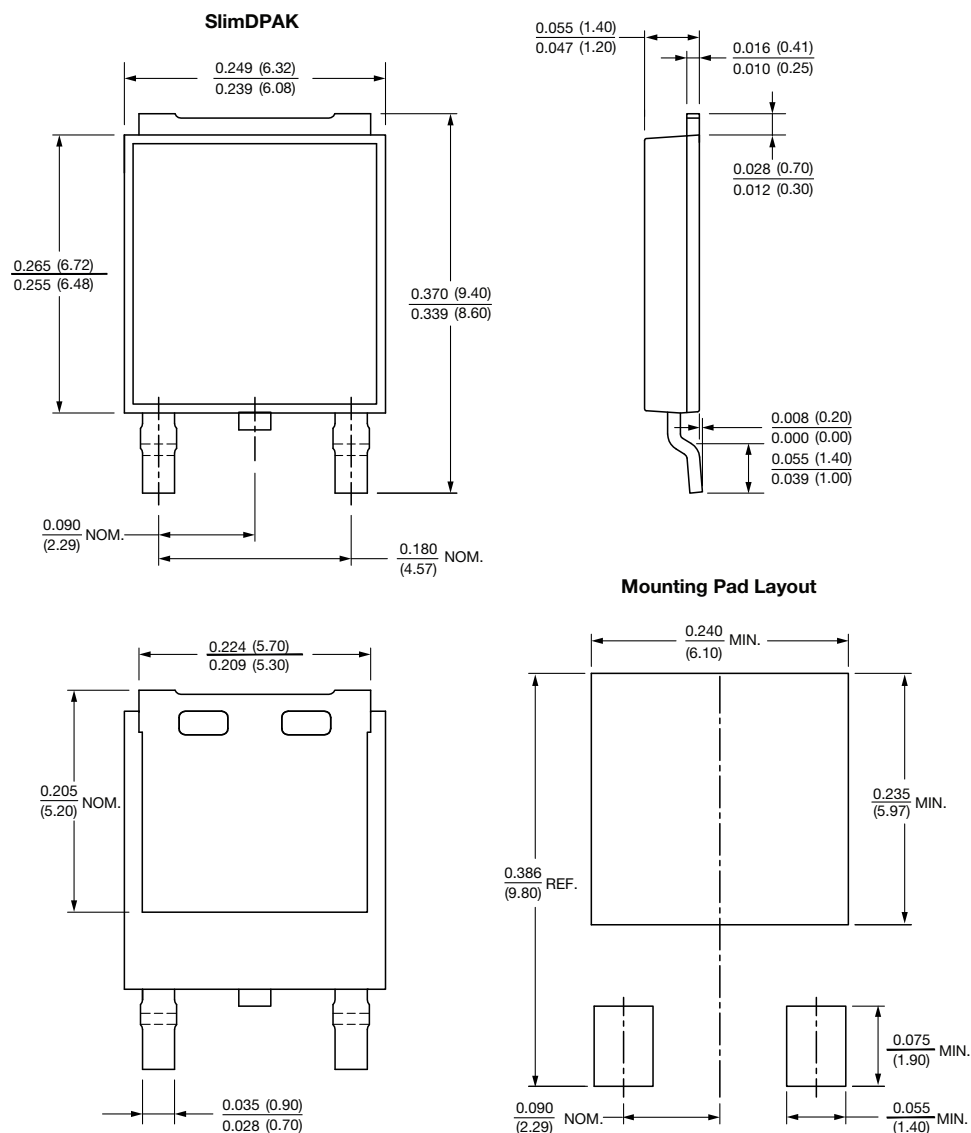


Fig. 7 - Typical Resistance Junction to Ambient vs. Copper Pad Areas

### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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